

# GP400DDM12

## **Dual Switch IGBT Module**

Advance Information DS5503-1.0 October 2001

### **FEATURES**

- High Thermal Cycling Capability
- 400A Per Switch
- Non Punch Through Silicon
- Isolated MMC Base with AIN Substrates

### **APPLICATIONS**

- High Reliability Inverters
- Motor Controllers
- Traction Drives
- Resonant Converters

The Powerline range of high power modules includes half bridge, dual, chopper and single switch configurations covering voltages from 600V to 3300V and currents up to 2400A.

The GP400DDM12 is a dual switch 1200V, n channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) ensuring reliability in demanding applications. This device is optimised for traction drives and other applications requiring high thermal cycling capability or very high reliability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise earthed heat sinks for safety.

## **ORDERING INFORMATION**

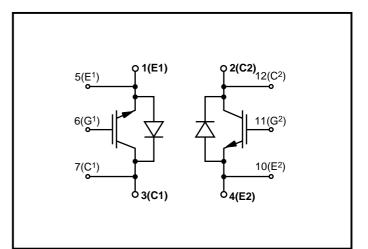
Order As:

GP400DDM12

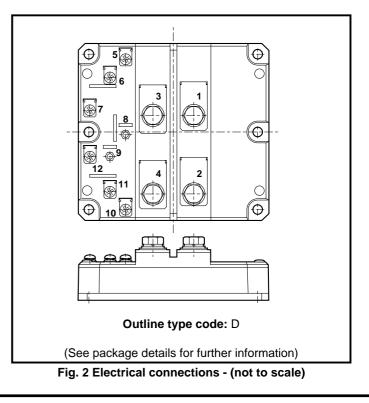
Note: When ordering, please use the whole part number.

KEY PARAMETERS	
V <sub>CES</sub>	1200V

V <sub>CE(sat)</sub>	(typ)	2.7V
I <sub>C</sub>	(max)	400A
Г <sub>С(РК)</sub>	(max)	800A









#### **ABSOLUTE MAXIMUM RATINGS - PER ARM**

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

#### T<sub>case</sub> = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
V <sub>CES</sub>	Collector-emitter voltage	V <sub>GE</sub> = 0V	1200	V
V <sub>GES</sub>	Gate-emitter voltage	-	±20	V
Ι <sub>c</sub>	Continuous collector current	$T_{case} = 80^{\circ}C$	400	А
I <sub>С(РК)</sub>	Peak collector current	1ms, T <sub>case</sub> = 105°C	800	А
P <sub>max</sub>	Max. transistor power dissipation	$T_{case} = 25^{\circ}C, T_{j} = 150^{\circ}C$	3470	W
V <sub>isol</sub>	Isolation voltage	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	4000	V

### THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance - transistor (per arm)	Continuous dissipation -	-	36	°C/kW
		junction to case			
R <sub>th(j-c)</sub>	Thermal resistance - diode (per arm)	Continuous dissipation -	-	80	°C/kW
		junction to case			
R <sub>th(c-h)</sub>	Thermal resistance - case to heatsink (per module)	Mounting torque 5Nm	-	8	°C/kW
		(with mounting grease)			
T <sub>j</sub>	Junction temperature	Transistor	-	150	°C
		Diode	-	125	°C
T <sub>stg</sub>	Storage temperature range	-	-40	125	°C
-	Screw torque	Mounting - M6	-	5	Nm
		Electrical connections - M4	-	2	Nm
		Electrical connections - M8	-	10	Nm



## **ELECTRICAL CHARACTERISTICS**

## T<sub>case</sub> = 25°C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
I <sub>CES</sub>	Collector cut-off current	$V_{GE} = 0V, V_{CE} = V_{CES}$	-	-	1	mA
		$V_{GE} = 0V, V_{CE} = V_{CES}, T_{case} = 125^{\circ}C$	-	-	20	mA
I <sub>GES</sub>	Gate leakage current	$V_{GE} = \pm 20V, V_{CE} = 0V$	-	-	±2	μA
V <sub>GE(TH)</sub>	Gate threshold voltage	$I_c = 120$ mA, $V_{ge} = V_{ce}$	4.5	5.5	7.5	V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> = 15V, I <sub>C</sub> = 800A	-	2.7	3.5	V
		$V_{GE} = 15V, I_{C} = 800A, T_{Case} = 125^{\circ}C$	-	3.2	4	V
I <sub>F</sub>	Diode forward current	DC, T <sub>case</sub> = 50°C	-	-	400	А
I <sub>FM</sub>	Diode maximum forward current	t <sub>p</sub> = 1ms	-	-	800	А
V <sub>F</sub>	Diode forward voltage	I <sub>F</sub> = 800A	-	2.2	2.5	V
		I <sub>F</sub> = 800A, T <sub>case</sub> = 125°C	-	2.3	2.5	V
C <sub>ies</sub>	Input capacitance	V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz	-	45	-	nF
L <sub>M</sub>	Module inductance	-	-	20	-	nH



## **ELECTRICAL CHARACTERISTICS**

### $T_{case} = 25^{\circ}C$ unless stated otherwise

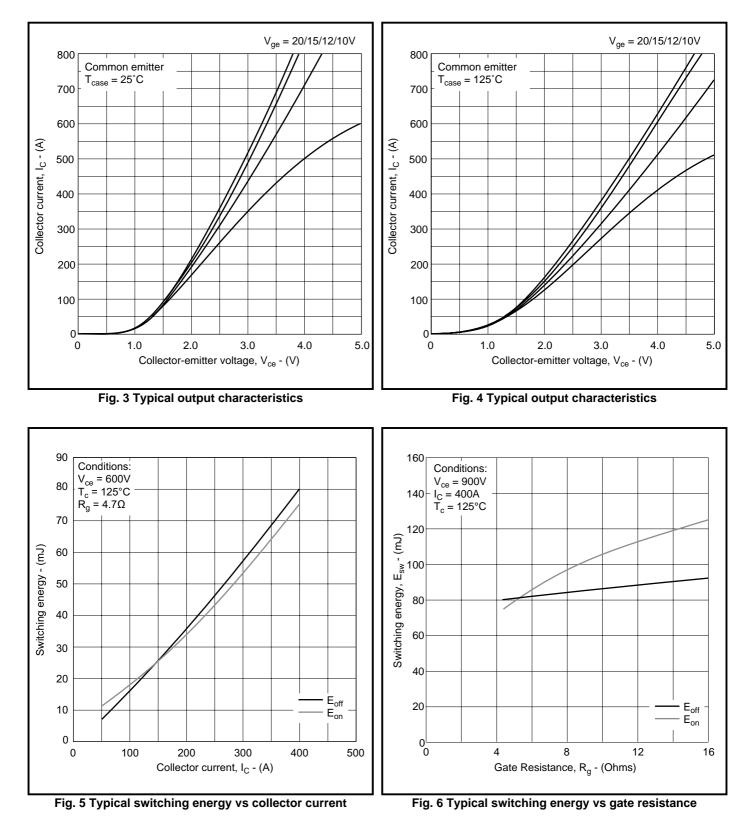
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
t <sub>d(off)</sub>	Turn-off delay time	I <sub>c</sub> = 400A	-	800	-	ns
t <sub>r</sub>	Fall time	$V_{GE} = \pm 15V$	-	110	-	ns
E <sub>OFF</sub>	Turn-off energy loss	$V_{CE} = 600V$	-	65	-	mJ
t <sub>d(on)</sub>	Turn-on delay time	$R_{G(ON)} = R_{G(OFF)} = 4.7\Omega$	-	700	-	ns
t,	Rise time	L ~ 100nH	-	170	-	ns
E <sub>on</sub>	Turn-on energy loss		-	45	-	mJ
Q <sub>rr</sub>	Diode reverse recovery charge	$I_{_{\rm F}}$ = 400A, $V_{_{\rm R}}$ = 50% $V_{_{\rm CES}}$ ,	-	30	-	μC
		$dI_F/dt = 2000A/\mu s$				

## T<sub>case</sub> = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
t <sub>d(off)</sub>	Turn-off delay time	I <sub>c</sub> = 400A	-	1000	-	ns
t <sub>f</sub>	Fall time	$V_{GE} = \pm 15V$	-	150	-	ns
E <sub>OFF</sub>	Turn-off energy loss	$V_{CE} = 600V$	-	80	-	mJ
t <sub>d(on)</sub>	Turn-on delay time	$R_{G(ON)} = R_{G(OFF)} = 4.7\Omega$	-	800	-	ns
t,	Rise time	L ~ 100nH	-	300	-	ns
E <sub>on</sub>	Turn-on energy loss		-	75	-	mJ
Q <sub>rr</sub>	Diode reverse recovery charge	$I_{_{\rm F}} = 400$ A, $V_{_{\rm R}} = 50\% V_{_{\rm CES}}$ ,	-	65	-	μC
		$dI_F/dt = 2000A/\mu s$				

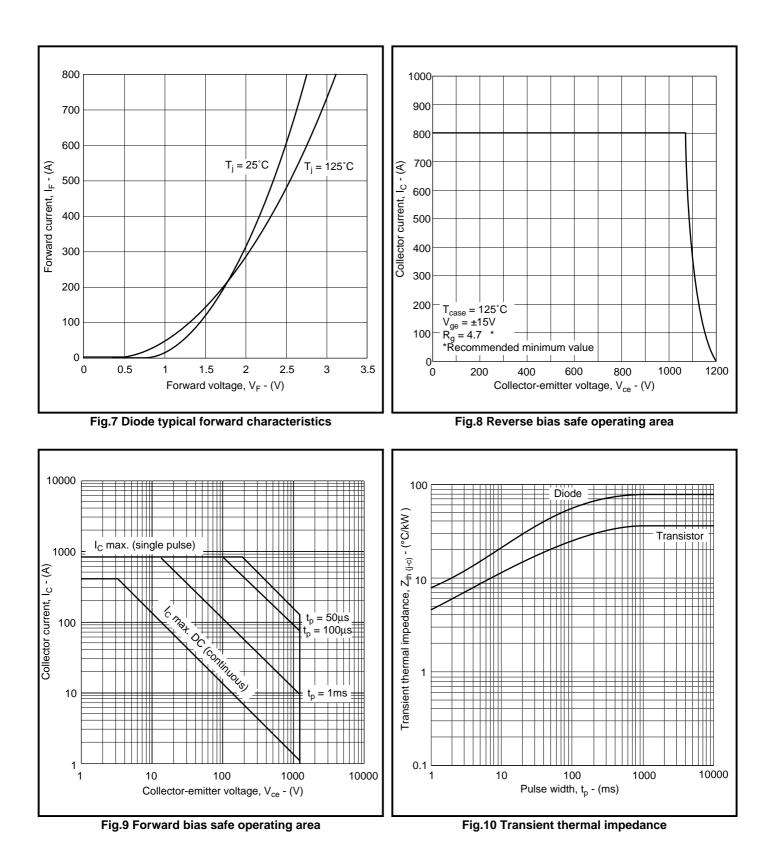


## **TYPICAL CHARACTERISTICS**



Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures. **www.dynexsemi.com** 







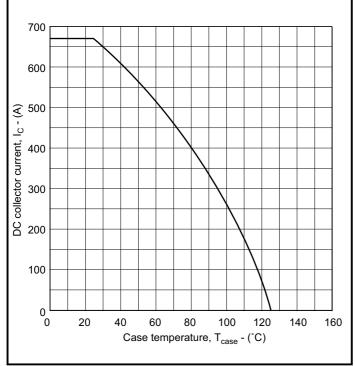


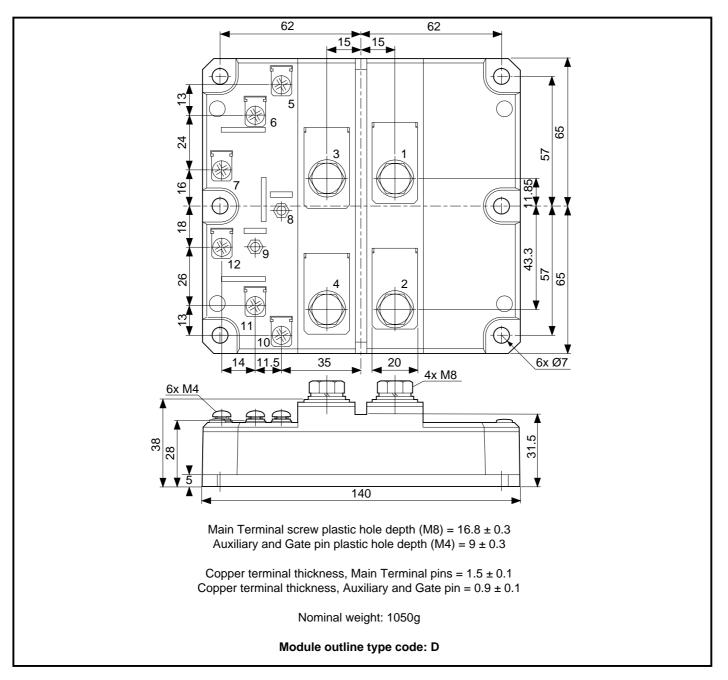
Fig.11 DC current rating vs case temperature

Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures. **www.dynexsemi.com** 



## PACKAGE DETAILS

For further package information, please visit our website or contact your nearest Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.







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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

No Annotation: The product parameters are fixed and the product is available to datasheet specification.

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